

Absolute Maximum Ratings

Storage Temperature -55°C to +125°C
 Operating Temperature -55°C to 100°C
 Lead Solder Temperature 260°C for 10s
 (1.6mm below seating plane)
 Average Input Current — I_F 25mA¹⁾
 Peak Input Current — I_F 50mA²⁾
 Peak Transient Input Current — I_F 1.0A
 (≤1μs pulse width, 300pps)

Reverse Input Voltage — V_R (Pin 3-2) 3V
 Input Power Dissipation 45mW³⁾
 Average Output Current — I_O (Pin 6) 8mA
 Peak Output Current 16mA
 Emitter-Base Reverse Voltage (Pin 5-7) 5V
 Supply and Output Voltage — V_{CC} (Pin 8-5),
 V_O (Pin 6-5) -0.5V to 15V
 Base Current — I_B (Pin 7) 5mA
 Output Power Dissipation 100mW⁴⁾

Switching Specifications at $T_A=25^\circ\text{C}$

$V_{CC} = 5V$, $I_F = 16mA$, unless otherwise specified

Parameter	Symbol	Min.	Max.	Units	Test Conditions	Note
Propagation Delay Time to Logic Low at Output (Fig. 1)	t_{PHL}		0.8	μs	$R_L = 1.9k\Omega$	7
Propagation Delay Time to Logic High at Output (Fig. 1)	t_{PLH}		0.8	μs	$R_L = 1.9k\Omega$	7

Parameter	Symbol	Min.	Max.	Units	Test Conditions	Note
Current Transfer Ratio	CTR	15	40	%	I _F = 16mA, V _O = 0.4V, V _{CC} = 4.5V	5
	CTR	8		%	I _F = 2mA, V _O = 5.0V, V _{CC} = 4.5V	
Logic Low Output Voltage	V _{OL}		0.4	V	I _F = 16mA, I _O = 2.4mA, V _{CC} = 4.5V	
Logic High Output Current	I _{OH}		50	nA	I _F = 0mA, V _O = V _{CC} = 10V	
	I _{OH}		25	μA	I _F = 0mA, V _O = V _{CC} = 10V, T _A = 70°C	
Input Forward Voltage	V _F		1.8	V	I _F = 20mA	
Input Reverse Current	I _R		50	μA	V _R = 3V	
Input-Output Insulation Leakage Current	I _{I-O}		1.0	μA	45% Relative Humidity, t = 5s V _{I-O} = 1500Vdc	6
Resistance (Input-Output)	R _{I-O}	10 ⁹		Ω	V _{I-O} = 100Vdc	6
Transistor DC Current Gain	h _{FE}	100	400	—	V _O = 5V, I _O = 3mA	
Capacitance	C _{I-O}		1.3	pF	f = 1 MHz	6
Breakdown Voltage Collector/Emitter	V _(BR) CEO	22		V	I _C = 10mA	8
Breakdown Voltage Collector/Base	V _(BR) CBO	40		V	I _C = 10μA	
Breakdown Voltage Emitter/Base	V _(BR) EBO	3		V	I _E = 10μA	
Collector/Base Current	I _{CBO}		50	nA	V _{CB} = 22V	

Notes:

1. Derate linearly above 70°C free-air temperature at a rate of 0.8mA/°C.
2. Derate linearly above 70°C free-air temperature at a rate of 1.6mA/°C.
3. Derate linearly above 70°C free-air temperature at a rate of 0.9mW/°C.
4. Derate linearly above 70°C free-air temperature at a rate of 2.0mW/°C.
5. CURRENT TRANSFER RATIO is defined as the ratio of output collector current, I_O, to the forward LED input current, I_F, times 100%.
6. Device considered a two-terminal device: Pins 1, 2, 3, and 4 shorted together and Pins 5, 6, 7, and 8 shorted together.
7. The 1.9 KΩ load represents 1 TTL unit load of 1.6 mA and the 5.6 KΩ pull-up resistor.
8. Duration of this test should not exceed 300 μs.

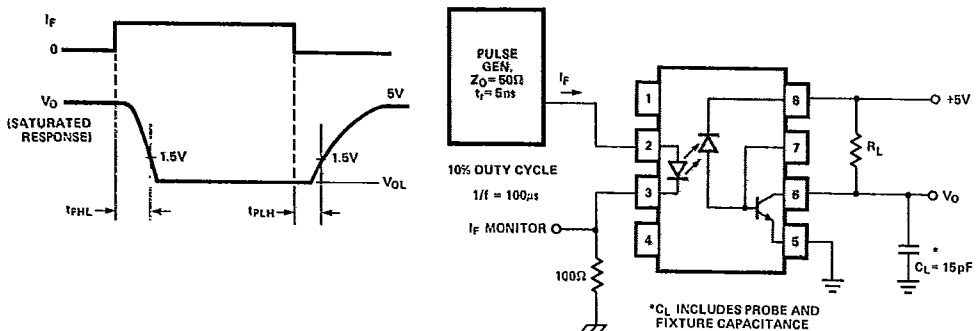


Figure 1. Switching Test Circuit.

CAUTION: The small junction sizes inherent to the design of this bipolar component increases the component's susceptibility to damage from electrostatic discharge (ESD). It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD.